


MATERIAL DECLARATION SHEET



Material Number	CM322522 Series (1R0~820)			
Product Line	Wound Chip Inductor			
Compliance Date	2022/9/2			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite Material	Ferrite	0.01	Iron oxide (Fe ₂ O ₃)	1309-37-1	63.0	13.20	20.00
				Nickel oxide (NiO)	1313-99-1	12.0	1.60	
				Zinc oxide (ZnO)	1314-13-2	18.0	4.40	
				Copper oxide(CuO)	1317-38-0	7.0	0.80	
2	Winding Wire	Copper	0.01	Copper(Cu)	7440-50-8	95.0	19.00	20.00
				Polyesterimide	-	5.0	1.00	
3	Terminal	Copper	0.02	Copper (Cu)	7440-50-8	95.0	38.00	40.00
				Tin (Sn)	7440-31-5	5.0	2.00	
4	Adhesive	Resin	0.002	BISPHENOL A DIGLYCIDYL ETHER RESIN	25068-38-6	65.0	2.60	4.00
				Dicyanodiamide	461-58-5	6.0	0.24	
				Titanium dioxide	13463-67-7	4.0	0.16	
				Silicon dioxide	7631-86-9	25.0	1.00	

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6	Molding Compound	Molding compound	0.006	silica	60676-86-0	69.0	8.28	12.00
				Antimony trioxide (Sb ₂ O ₃)	1309-64-4	2.5	0.30	
				Formaldehyde, polymer with 2-(chloromethyl)oxirane and 2-methylphenol	29690-82-2	15.0	1.80	
				Phenol-Formaldehyde Resin	9003-35-4	10.0	1.20	
				Brominated epoxy resin	40039-93-8	2.5	0.30	
				Carbon black	1333-86-4	1.0	0.12	
7	Solder	Tin	0.002	Tin (Sn)	7440-31-5	100.0	4.00	4.00
		Total weight	0.050					

This Document was updated on: **2022/9/2**

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.